



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



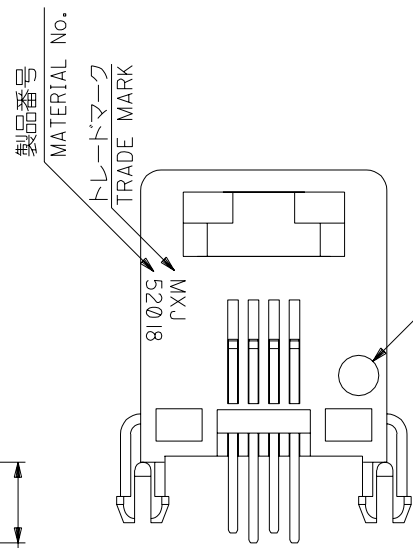
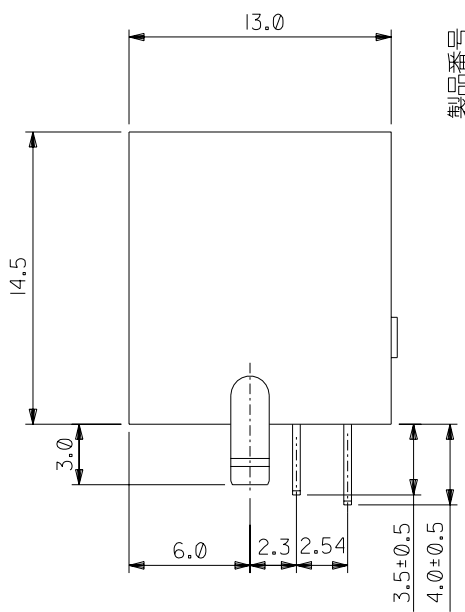
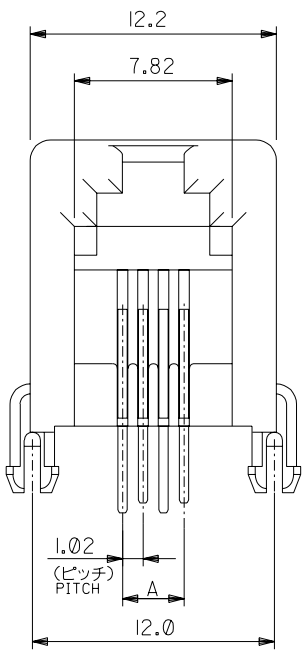
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

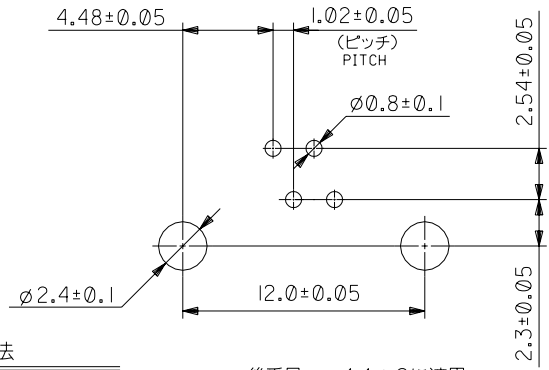
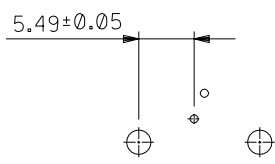
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





注) NOTES

- 材質 MATERIAL  
ハウジング: ガラス入りポリエステル UL94V-0  
HSG.: POLYESTER G.F.15% UL94V-0  
ターミナル: リン青銅  
TERM.: PHOSPHOR BRONZE
- メッキ仕様 PLATING  
接点部: 金メッキ、表参照  
CONTACT AREA: GOLD PER TABLE  
半田付け部: 錫メッキ 1.0µmMIN.  
SOLDER AREA: TIN 1.0 MICROMETER MINIMUM.  
下地メッキ: ニッケルメッキ 1.0µmMIN.  
UNDERPLATE: NICKEL 1.0 MICROMETER MINIMUM.
- 推奨基板厚: t=1.6±0.05  
RECOMMENDED P.C.B. THICKNESS: 1.6±0.05
- 金メッキ厚標示  
COLOR CODING TO INDICATE GOLD PLATING  
黄色: 0.1µmMIN.  
YELLOW: 0.1 MICROMETER MINIMUM.  
緑色: 0.38µmMIN.  
GREEN: 0.38 MICROMETER MINIMUM.  
オレンジ色: 0.76µmMIN.  
ORANGE: 0.76 MICROMETER MINIMUM.  
無色: 1.27µmMIN.  
UNMARKED: 1.27 MICROMETER MINIMUM.
- ハウジングの色は、グレイ。  
HOUSING COLOR IS GRAY.
- 本製品は52018-4\*\*5の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52018-4\*\*5.



後番号 -42\*6に適用  
MATERIAL NO. SUFFIX -42\*6

基板穴推奨寸法  
RECOMMENDED P.C.B. LAYOUT  
(ジャック取付け側)  
(JACK ASS'Y SIDE)

後番号 -44\*6に適用  
MATERIAL NO. SUFFIX -44\*6

4	4	3.05	1.27	52018-4446
			0.76	-4436
			0.38	-4426
			0.1	-4416
4	2	1.02	1.27	52018-4246
ポジション POSITION	極数 CIRCUITS	(A)	金メッキ厚 (µmMIN.) GOLD PLATING THK(MIN.) (µmMIN.)	製品番号 MATERIAL NO.

64 NO. DRWN: CHK: APPR:	63 NO. DRWN: CHK: APPR:	62 NO. DRWN: CHK: APPR:	61 NO. DRWN: CHK: APPR:	0 REV
新製/作成 RELEASED 04/05/13	04/05/13	04/05/13	04/05/13	
DRWN: M.NAGATA	DRWN: M.NAGATA	CHK: K.TOJO	CHK: K.TOJO	
APPR: M.SASAO	APPR: M.SASAO			

MATERIAL 材料	注参照 SEE NOTES
FINISH 仕上げ	注及び表参照 SEE NOTES AND CHART
WIRE RANGE 適用電線範囲	#
INS. RANGE 被覆外径	#

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE 4:1	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH
10 UNDER 未満	±0.2	
10 OVER 以上	±0.25	
30 UNDER 未満	±0.3	
30 OVER 以上	±0.3	
ANGLE 角度	±3°	

MODEL NO. 52018-4**6	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT REV
DRAWN BY & DATE M.NAGATA 04/05/13	TITLE: MODULAR JACK HOUSING ASS'Y -LEAD FREE-	
CHECKED BY & DATE K.TOJO 04/05/13	MOLEX MOLEX INCORPORATED	
APPROVED BY & DATE M.SASAO 04/05/13	CAD FILENAME SD-52018-002.S01	MATERIAL NO. DRAWING NO. SD-52018-002
		SHEET NO. 1 OF 1
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B